



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10C181JB8NNWC
- Description : CAP, 180 pF, 50V, ±5%, C0G, 0603

A. Samsung Part Number

			<u>CL</u> ①	<u>10</u> ②	<u>C</u> 3	<u>181</u> ④	<u>J</u> 5	<u>B</u> 6	<mark>8</mark> 7	<u>N</u> 8	<u>N</u> 9	<u>W</u> 10	<u>C</u> 10	
1 S	eries	Samsung Multi-layer Ceramic Capacitor												
② Si	ize	0603	(inch co	ode)		L:	1.6	± 0.1		mm		W:	0.8 ± 0.1	mm
3 Di	ielectric	C0G					8	Inne	r ele	ctroc	le		Ni	
④ C	apacitance	180	рF					Term	ninat	tion			Cu	
5 C	apacitance	±5	%					Plati	ng				Sn 100%	(Pb Free)
to	olerance						9	Prod	luct				Normal	
6 R	ated Voltage	50	V				10	Spec	cial				Product for N	Network application
⑦ TI	hickness	0.8	± 0.1	mm			1	Pack	agir	ng			Cardboard T	ype, 7" reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1₩±10% 0.5~5Vrms						
Q	1000 min							
Insulation	10,000Mohm or 500Mohm ⋅ <i>μ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance No abnormal exterior appearance		Microscope (×10)						
Withstanding	No dielectric breakdown or	300% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	COG							
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change :	Bending to the limit (1mm)						
	within $\pm 5\%$ or $\pm 0.5_{pF}$ whichever is larger	with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120℃ for 10~30sec.)						
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger							
	Tan δ, IR : initial spec.							

	Performance	Test condition						
Vibration Test	Capacitance change :	Amplitude : 1.5mm						
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)						
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)						
Moisture	Capacitance change :	With rated voltage						
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs						
	Q : 200 min							
	IR : 500Mohm or 25Mohm · μF							
	Whichever is Smaller							
High Temperature	Capacitance change :	With 200% of the rated voltage						
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature						
	Q : 350 min	1000+48/-0hrs						
	IR : 1000Mohm or 50Mohm · <i>μ</i> F							
	Whichever is Smaller							
Temperature	Capacitance change :	1 cycle condition						
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperature \rightarrow 25 °C						
	Tan δ, IR : initial spec.	\rightarrow Max. operating temperature \rightarrow 25 °C						
		5 cycle test						

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^\circ\!\mathrm{C}$, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.